

# PSMN2R0-30YL

## N-channel TrenchMOS logic level FET

Rev. 01 — 10 September 2008

Preliminary data sheet

## 1. Product profile

### 1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in industrial and communications applications.

### 1.2 Features and benefits

- High efficiency due to low switching and conduction losses
- Suitable for logic level gate drive sources

### 1.3 Applications

- Class-D amplifiers
- Motor control
- DC-to-DC converters
- Server power supplies

### 1.4 Quick reference data

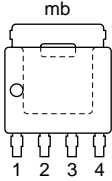
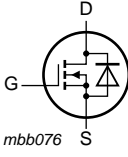
Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 150\text{ °C}$	-	-	30	V
$I_D$	drain current	$T_{mb} = 25\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; see <a href="#">Figure 1</a> ; see <a href="#">Figure 3</a> ;	[1]	-	100	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 2</a>	-	-	97	W
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$V_{GS} = 4.5\text{ V}$ ; $I_D = 10\text{ A}$ ; $V_{DS} = 12\text{ V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	7.5	-	nC
<b>Static characteristics</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$ ; $I_D = 15\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 12</a>	-	1.56	2	mΩ

[1] Continuous current is limited by package.

## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

**SOT669  
(LFAK)**

## 3. Ordering information

Table 3. Ordering information

Type number	Package		Description	Version
	Name			
PSMN2R0-30YL	LFAK		Plastic single-ended surface-mounted package (LFAK); 4 leads	SOT669

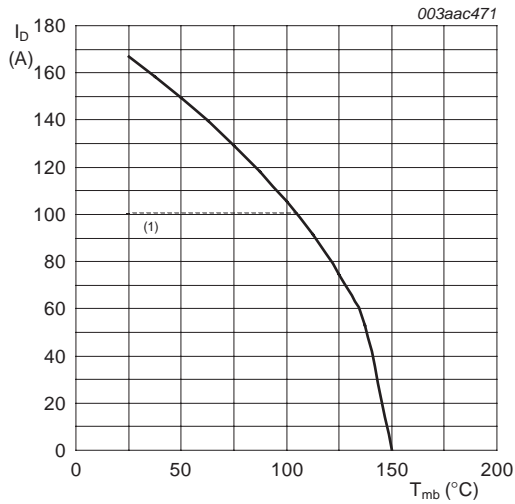
## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

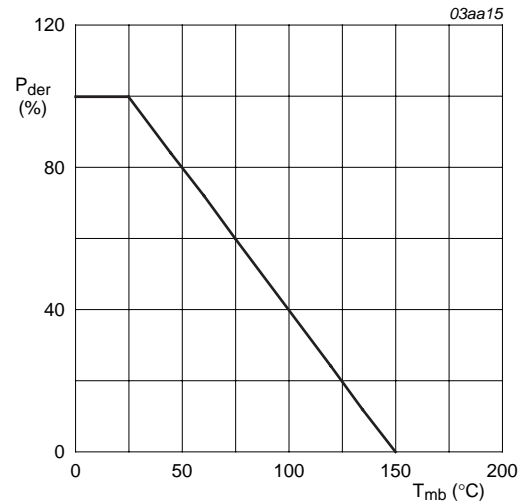
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 150\text{ °C}$	-	30	V
$V_{DGR}$	drain-gate voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 150\text{ °C}$ ; $R_{GS} = 20\text{ k}\Omega$	-	30	V
$V_{GS}$	gate-source voltage		-20	20	V
$I_D$	drain current	$V_{GS} = 10\text{ V}$ ; $T_{mb} = 100\text{ °C}$ ; see <a href="#">Figure 1</a> ;	-	100	A
		$V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 1</a> ; <a href="#">Figure 3</a> ;	-	100	A
$I_{DM}$	peak drain current	$t_p \leq 10\text{ }\mu\text{s}$ ; pulsed; $T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 3</a>	-	667	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 2</a>	-	97	W
$T_{stg}$	storage temperature		-55	150	°C
$T_j$	junction temperature		-55	150	°C
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ °C}$ ; <a href="#">[1]</a>	-	100	A
$I_{SM}$	peak source current	$t_p \leq 10\text{ }\mu\text{s}$ ; pulsed; $T_{mb} = 25\text{ °C}$	-	667	A
<b>Avalanche ruggedness</b>					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; $I_D = 100\text{ A}$ ; $V_{sup} \leq 30\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; unclamped	-	151	mJ

[1] Continuous current is limited by package.



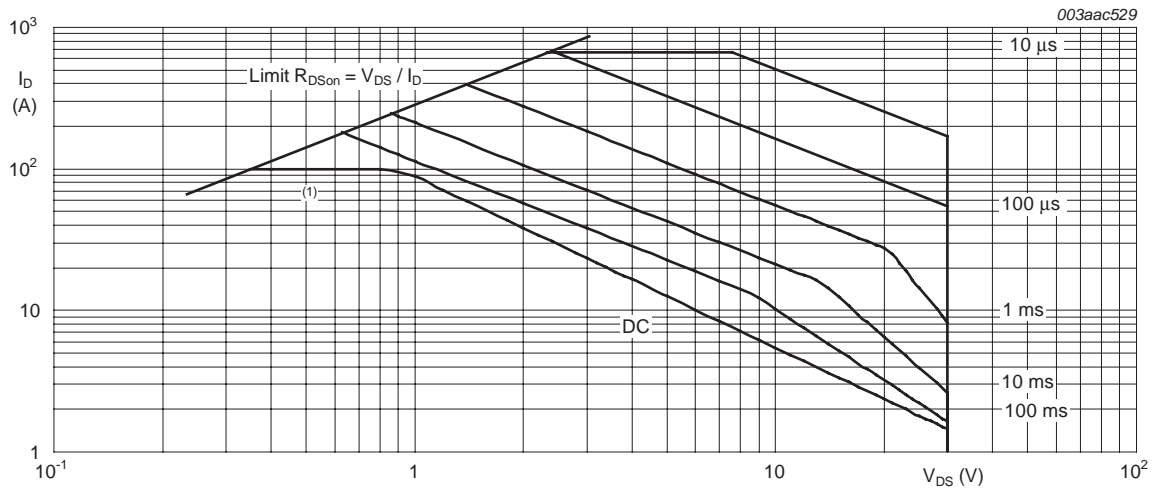
$V_{GS} \geq 10V$   
 (1) Capped at 100 A due to package.

**Fig 1. Continuous drain current as a function of mounting base temperature**



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100\%$$

**Fig 2. Normalized total power dissipation as a function of mounting base temperature**



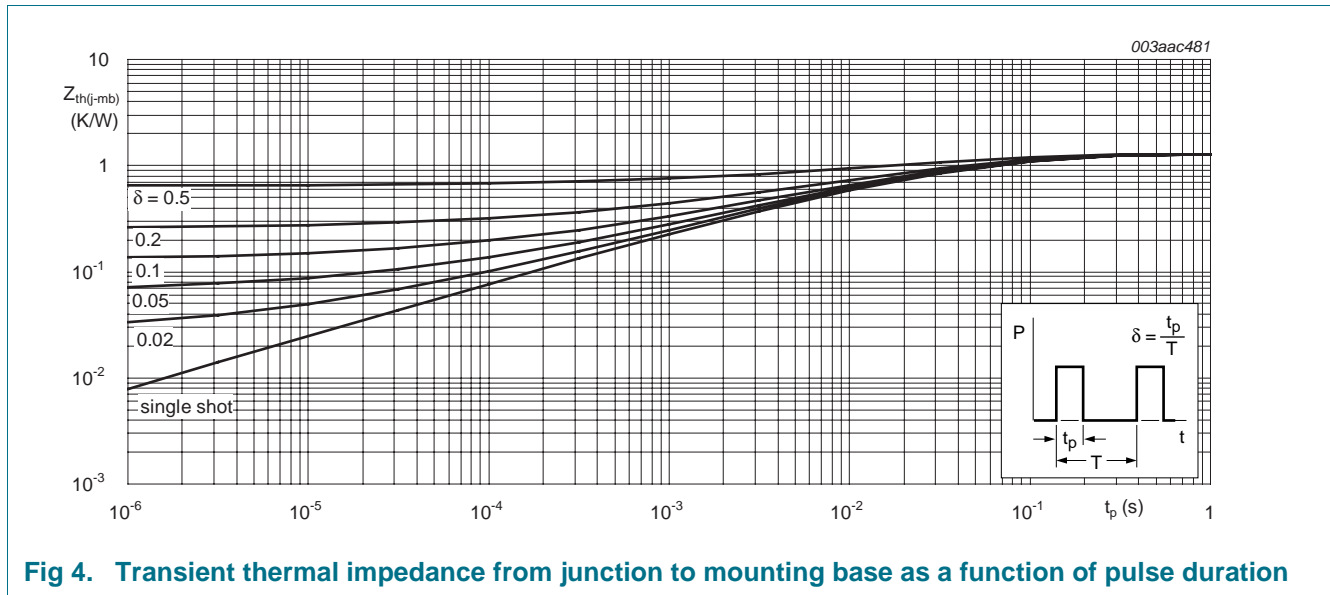
$T_{mb} = 25^\circ C; I_{DM}$  is single pulse  
 (1) Capped at 100 A due to package.

**Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage**

### 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see <a href="#">Figure 4</a>	-	-	1.28	K/W



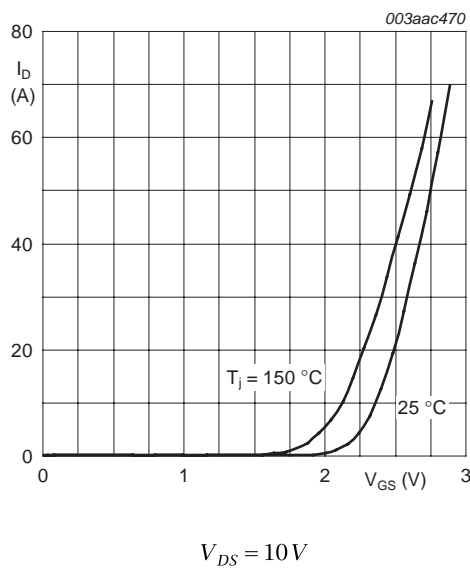
## 6. Characteristics

**Table 6. Characteristics**

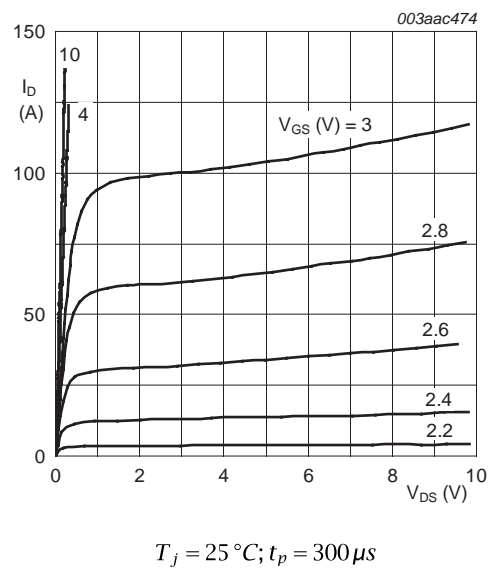
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	30	-	-	V
		$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 10</a> ; see <a href="#">Figure 11</a>	1.3	1.7	2.15	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 10</a>	0.65	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 10</a>	-	-	2.45	V
$I_{DSS}$	drain leakage current	$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150 \text{ }^\circ\text{C}$	-	-	100	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	100	nA
		$V_{GS} = -16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	-	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 12</a>	-	2.15	3.2	m $\Omega$
		$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 150 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 13</a>	-	-	3.3	m $\Omega$
		$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 12</a>	-	1.56	2	m $\Omega$
$R_G$	gate resistance	$f = 1 \text{ MHz}$	-	0.75	-	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 10 \text{ A}; V_{DS} = 12 \text{ V}; V_{GS} = 10 \text{ V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	64	-	nC
		$I_D = 0 \text{ A}; V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}$	-	59	-	nC
		$I_D = 10 \text{ A}; V_{DS} = 12 \text{ V}; V_{GS} = 4.5 \text{ V}$ ; see <a href="#">Figure 14</a>	-	30	-	nC
$Q_{GS}$	gate-source charge	$I_D = 10 \text{ A}; V_{DS} = 12 \text{ V}; V_{GS} = 4.5 \text{ V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	9.8	-	nC
$Q_{GD}$	gate-drain charge		-	7.5	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	6.6	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	3.2	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$V_{DS} = 12 \text{ V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	2.34	-	V
$C_{iss}$	input capacitance	$V_{DS} = 12 \text{ V}; V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$ ; see <a href="#">Figure 16</a>	-	3980	-	pF
$C_{oss}$	output capacitance		-	857	-	pF
$C_{rss}$	reverse transfer capacitance		-	347	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 12 \text{ V}; R_L = 0.5 \text{ } \Omega; V_{GS} = 4.5 \text{ V}; R_{G(ext)} = 4.7 \text{ } \Omega$	-	39	-	ns
$t_r$	rise time		-	65	-	ns
$t_{d(off)}$	turn-off delay time		-	63	-	ns
$t_f$	fall time		-	28	-	ns

Table 6. Characteristics ...continued

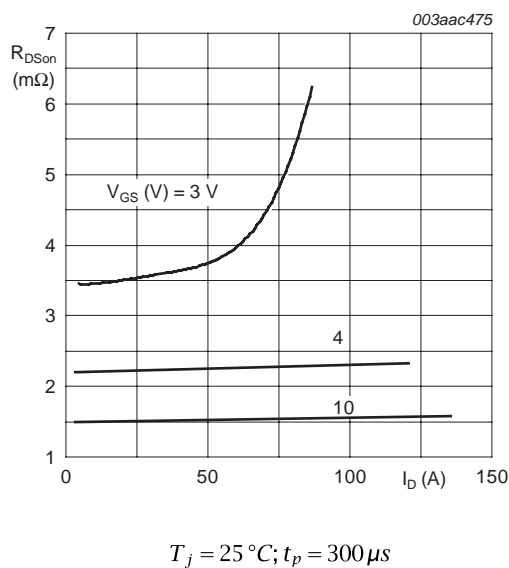
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 25$ A; $V_{GS} = 0$ V; $T_j = 25$ °C; see <a href="#">Figure 17</a>	-	0.88	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 20$ A; $di_S/dt = -100$ A/s; $V_{GS} = 0$ V;	-	43	-	ns
$Q_r$	recovered charge	$V_{DS} = 20$ V	-	49	-	nC



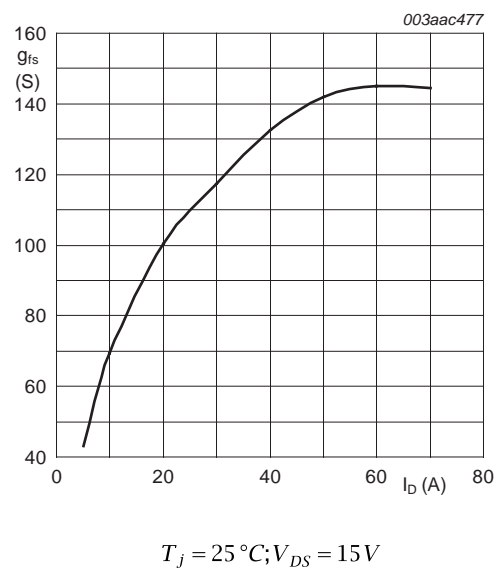
**Fig 5. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



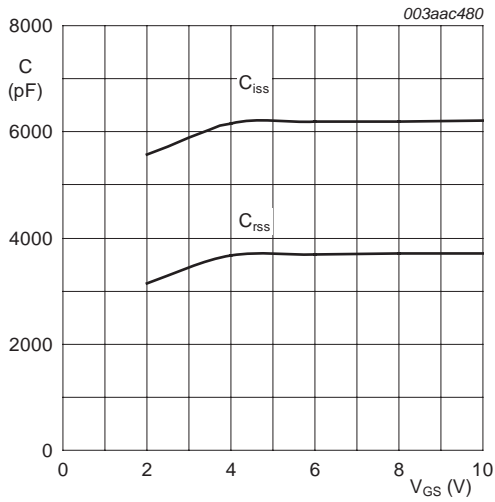
**Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values**



**Fig 7. Drain-source on-state resistance as a function of drain current; typical values**

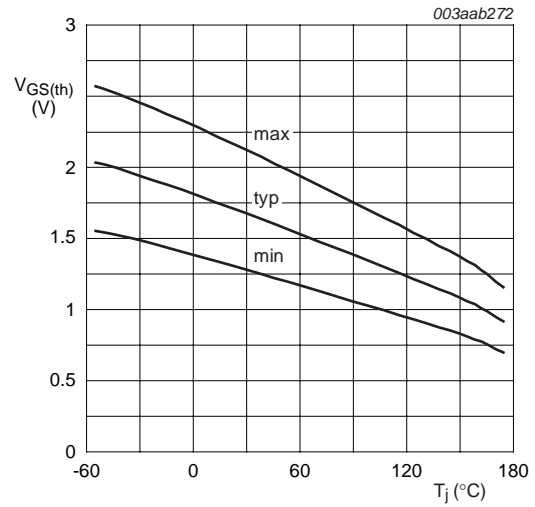


**Fig 8. Forward transconductance as a function of drain current; typical values**



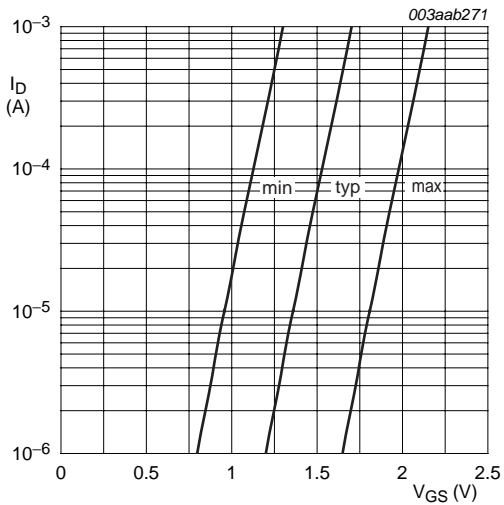
$V_{DS} = 0V; f = 1MHz$

**Fig 9. Input and reverse transfer capacitances as a function of gate-source voltage; typical values**



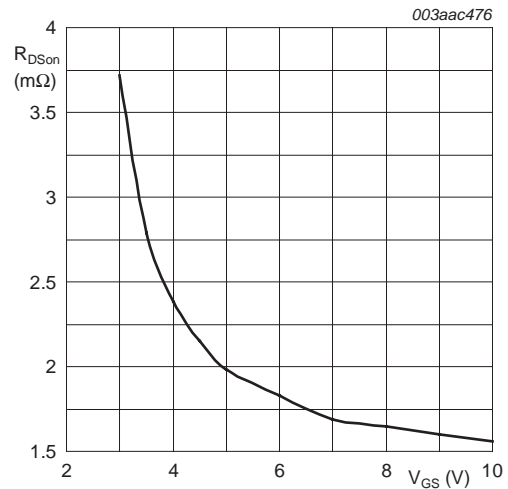
$I_D = 1mA; V_{DS} = V_{GS}$

**Fig 10. Gate-source threshold voltage as a function of junction temperature**



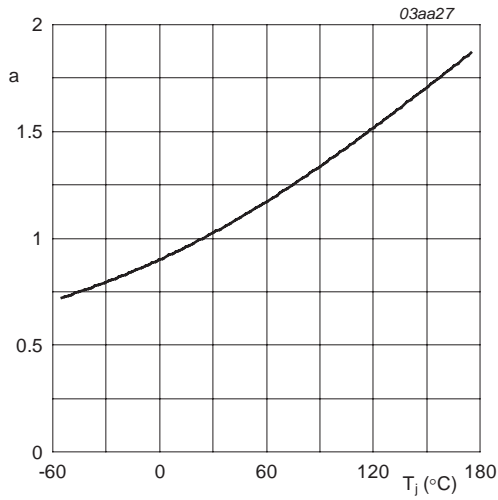
$T_j = 25^\circ C; V_{DS} = 5V$

**Fig 11. Sub-threshold drain current as a function of gate-source voltage**



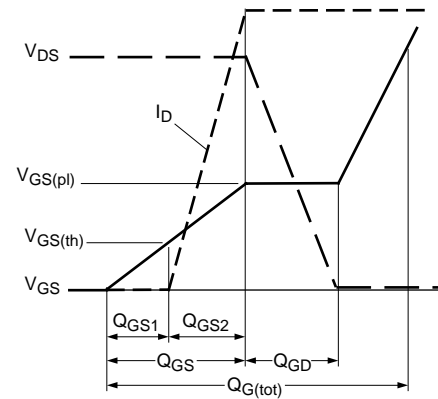
$T_j = 25^\circ C; I_D = 15A$

**Fig 12. Drain-source on-state resistance as a function of gate-source voltage; typical values**



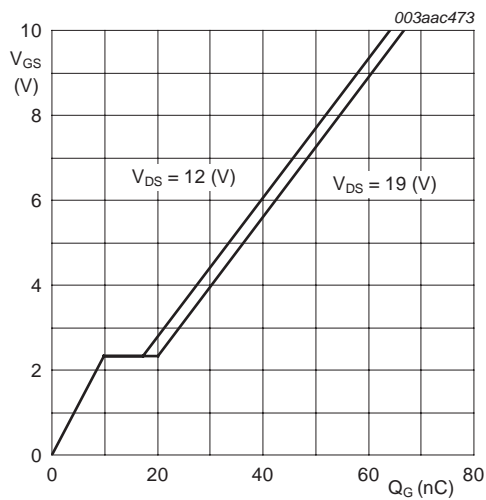
$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}C)}}$$

**Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature**



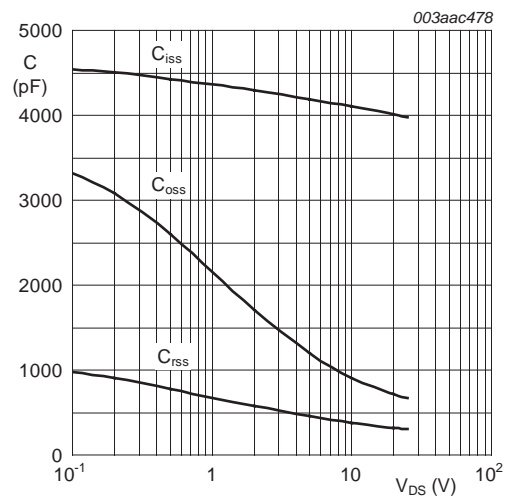
003aaa508

**Fig 14. Gate charge waveform definitions**



$T_j = 25^{\circ}C; I_D = 10 A$

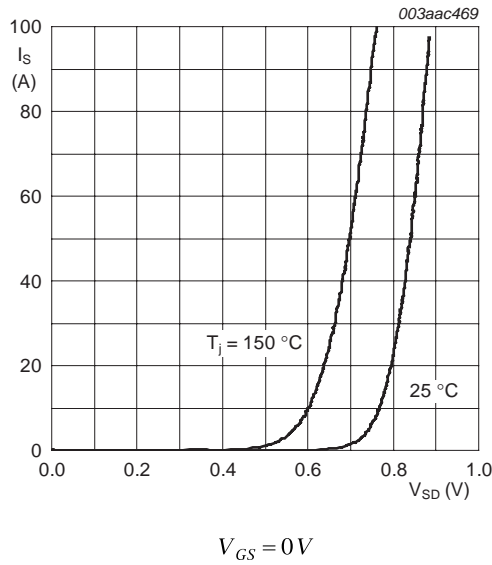
**Fig 15. Gate-source voltage as a function of gate charge; typical values**



$V_{GS} = 0 V; f = 1 MHz$

**Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**





**Fig 17. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values**

## 7. Package outline

Plastic single-ended surface-mounted package (LPAK); 4 leads

SOT669

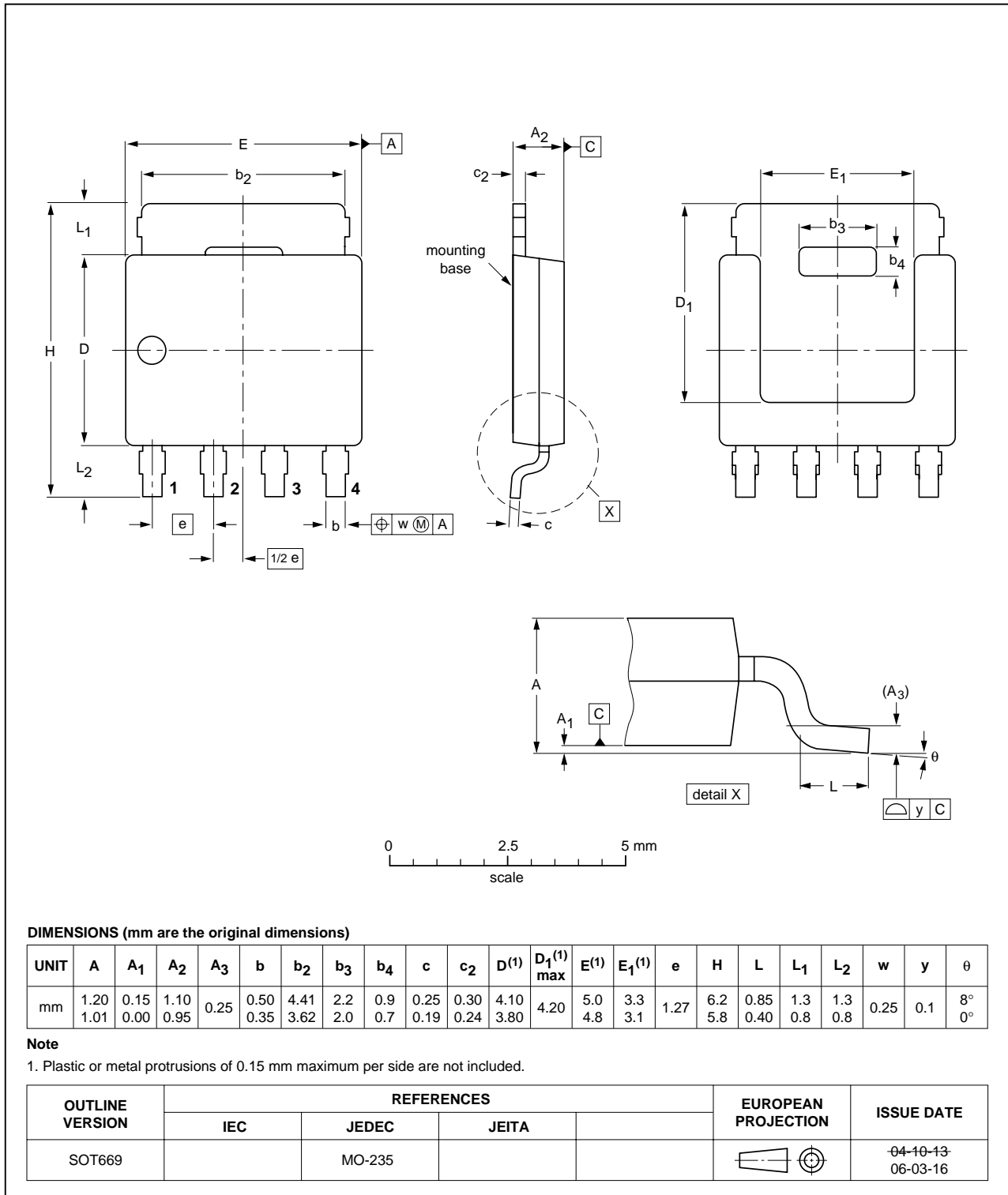


Fig 18. Package outline SOT669 (LPAK)

## 8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN2R0-30YL_1	20080910	Preliminary data sheet	-	-

## 9. Legal information

### 9.1 Data sheet status

Document status [1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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